

SOLDER PASTE



Overview

Type: Assembly Tools, Hand Tools

Product name: XG-50

Attributes: Solder Paste Flux

Packing: Case

Weight: 35g

Alloy: Sn63/Pb37

Features: Free lead solder, High Quality

Application: for BGA Soldering Iron Station Flux Cream

Material: Plastic Bottle

Function: for Phone PCB Motherboard Welding Repairing Flux Paste

Product Features:

Lead free MECHANIC BGA solder flux paste soldering tin cream professional for BGA soldering iron station.

Unique recipes, perfect performance, easy to weld, solder bright and full, no weld, false welding and so on.

Good soldering and welding tools.

Free lead solder paste, 183 °C, the degree of melting point, easy welding, easy molding.

Product Specifications:

Material: Plastic+solder paste.

Single package size: 15X15X15 cm

Type: XG-50 , 35g

Alloy: Sn63/Pb37.

Brand Name: Mechanic

Microns: 25-45um.

Application: for BGA motherboard soldering iron station flux cream.

Function: Mobile phone chips repair, computer and digital service industries, high-precision circuit board SMT soldering, BGA welding process, etc.

Hi-Preformance.

Storage Condition:0-10°C.

Compatiable: for phone PCB BGA soldering repairing

Warning:

Harmful by inhalation and if swallowed.

Danger of cumulative effects.

Keep away from food,drink and animal feeding stuffs.

When using do not eat,Drink or smoke.

Avoid prolonged or repeated contact of any skin with solder paste. In case of solder paste ingestion see a doctor immediately.

Store container welll closed and cool(at 0 to 10°)..